

# Specification of MEMS Microphone

(RoHS Compliance & Halogen Free)

**Customer Name:** 

**Customer Model:** 

GoerTek Model: S12OT421-008

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# 1 Security Warning

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## 2 Publication History

Version	Date	Description	Author	Approved
1.0	2018.07.27	New Design	Jasen	Daniel



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## 1 Introduction:

MEMS MIC which is able to endure reflow temperature up to 260  $^{\circ}\mathrm{C}$  for 50 seconds can be used in SMT process. It is widely used in telecommunication and electronics device such as mobile phone, MP3, PDAs etc.

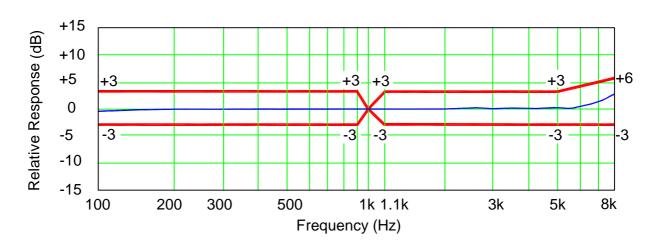
# 2 Test Condition (Vs=2.0V,L=50cm)

StandardConditions (As IEC 60268-4)	Temperature	Humidity	Air pressure	
Environment Conditions	+15℃~+35℃	25%RH~75%RH	86kPa $\sim$ 106kPa	
Basic Test Conditions	+20±2℃	60%RH~70%RH	86kPa∼106kPa	

## 3 Electrical Characteristics

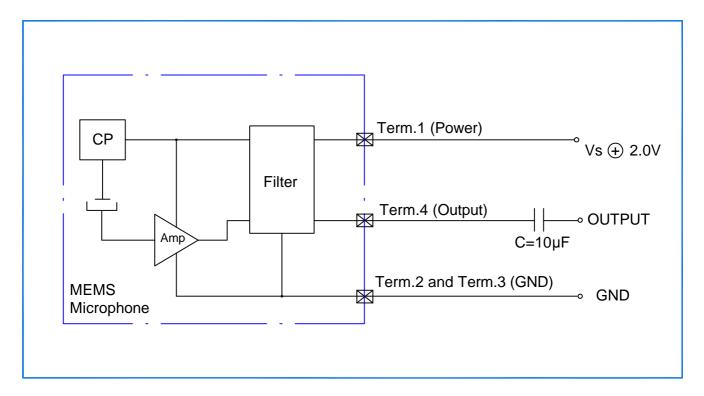
Item	Symbol	Test Conditions	Min	Тур	Max	Unit
Sensitivity	S	f=1kHz, Pin=1Pa	-43	-42	-41	dB
Output Impedance	Zout	f=1kHz, Pin=1Pa			400	Ω
Directivity	D(θ)		Omnidirectional			
Current Consumption	ı		50		150	μΑ
S/N Ratio	S/N(A)	f=1kHz, Pin=1Pa A-Weighted		58		dB
Decreasing Voltage Characteristic	△S	f=1kHz, Pin=1Pa Vs=3.61.5V	No Change			
Operating Voltage Range	Vs		1.5		3.6	٧
Total Harmonic Distortion	THD	110dB SPL@ f=1kHz			1	%

# **4 Frequency Response Curve Limits**

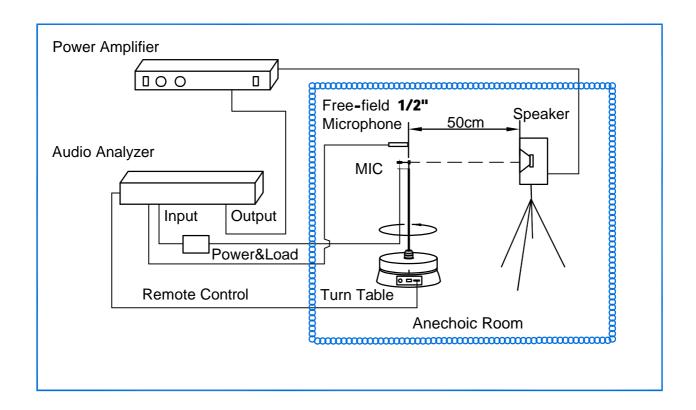




#### **5 Measurement Circuit**



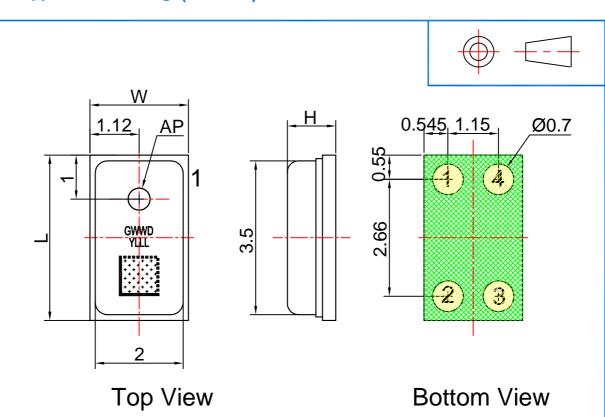
## 6 Test Setup Drawing





## 7 Mechanical Characteristics

## 7.1 Appearance Drawing (Unit: mm)



Pin Output			
Pin# Function			
1 Power			
2 GND			
3 GND			
4 Output			

Item	Dimension	Tol.(±)	Units
Length	3.76	0.1	mm
Width	2.24	0.1	mm
Height	1.1	0.1	mm
AP (Acoustic port)	0.5	0.1	mm

Note: 1. Tolerance ±0.10mm unless otherwise specified.

2. Identification Number Convention: Job Identification Number.

Identification Number

G W W D

G: GoerTek

Y:Year

www:Week D:Day

LLL: Lot Number

2D Code

#### 7.2 Weight

The weight of the MIC is Less than 0.04g.



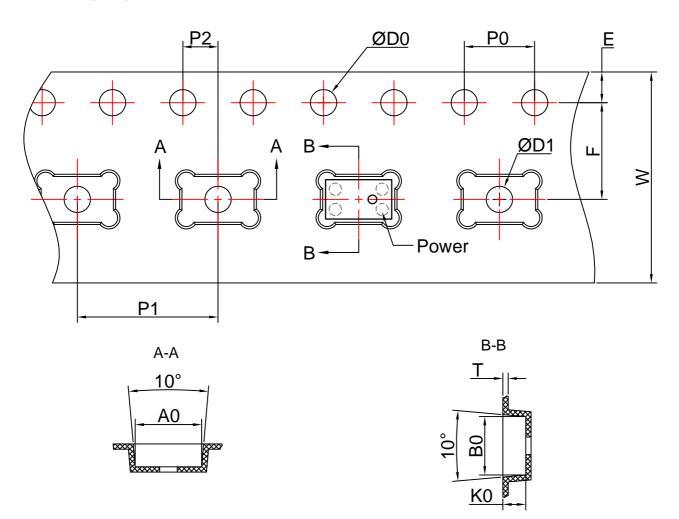
# 8 Reliability

8.1 Vibration Test	To be no interference in operation after vibrations, 4 cycles, from 20 to 2,000Hz in each direction(X,Y,Z), 48 minutes, using peak acceleration of 20g, sensitivity should vary within $\pm 3$ dB from initial sensitivity. (The measurement to be done after 2 hours of conditioning at $\pm 15^{\circ}$ C $\pm 435^{\circ}$ C, R.H 25% $\pm 75^{\circ}$ C)
8.2 Drop Test	To be no interference in operation after dropped to 1.0cm steel plate 18 times from 1.5 meter height, sensitivity should vary within ±3dB from initial sensitivity. (The measurement to be done after 2 hours of conditioning at +15°C~+35°C, R.H 25%~75%)
8.3 Temperature Test	a) After exposure at +125 °C for 200 hours, sensitivity should vary within ±3dB from initial sensitivity.  (The measurement to be done after 2 hours of conditioning at +15 °C ~+35 °C, R.H 25% ~75%)  b) After exposure at -40 °C for 200 hours, sensitivity should vary within ±3dB from initial sensitivity.  (The measurement to be done after 2 hours of conditioning at +15 °C ~+35 °C, R.H 25% ~75%)
8.4 Humidity Test	After exposure at +85℃ and 85% relative humidity for 200 hours, sensitivity should vary within ±3dB from initial sensitivity.  (The measurement to be done after 2 hours of conditioning at +15℃~+35℃, R.H 25%~75%)
8.5 Mechanical Shock Test	Then subject samples to three one-half sine shock pulses (3000 g for 0.3 milliseconds) in each direction (for six axes in total) along each of the three mutually perpendicular axes for a total of 18 shocks, sensitivity should vary within $\pm 3$ dB from initial sensitivity. (The measurement to be done after 2 hours of conditioning at $\pm 15^{\circ}$ C $\pm 35^{\circ}$ C, R.H $\pm 25^{\circ}$ C $\pm 35^{\circ}$ C)
8.6 Thermal Shock Test	After exposure at -40 $^{\circ}$ C for 30 minutes, at +125 $^{\circ}$ C for 30 minutes (change time 20 seconds) 5 cycles, sensitivity should vary within ±3dB from initial sensitivity. (The measurement to be done after 2 hours of conditioning at +15 $^{\circ}$ C $^{\circ}$ +35 $^{\circ}$ C, R.H 25% $^{\circ}$ 75%)
8.7 Reflow Test	Adopt the reflow curve of item 12.3, after five reflows, sensitivity should vary within $\pm 2dB$ from initial sensitivity. (The measurement to be done after 2 hours of conditioning at $\pm 15^{\circ}$ C $\pm 35^{\circ}$ C, R.H $\pm 25^{\circ}$ C $\pm 35^{\circ}$ C, R.H $\pm 25^{\circ}$ C $\pm 35^{\circ}$ C, R.H $\pm 25^{\circ}$ C $\pm 35^{\circ}$ C $\pm 35^{\circ}$ C, R.H $\pm 25^{\circ}$ C $\pm 35^{\circ}$ C $\pm 35^$
8.8 Electrostatic Discharge Test	Under C=150pF, R=330ohm. Tested to ±8KV contact to the case and tested to ±2kV contact to I/O terminals.10 times. Grounding. Sensitivity should vary within ±2dB from initial sensitivity.



## 9 Package

## 9.1 Tape Specification



## The Dimensions as Follows:

ITEM	W	E	F	ØD0	ØD1
DIM(mm)	12.0±0.30	1.75±0.10	5.5±0.05	1.50-0.10	1.0 MIN
ITEM	P0	10P0	P1	A0	В0
DIM(mm)	4.00±0.10	40.00±0.20	8.00±0.10	4.10±0.10	2.60±0.10
ITEM	K0	P2	Т		
DIM(mm)	1.35±0.10	2.00±0.05	0.30±0.05		

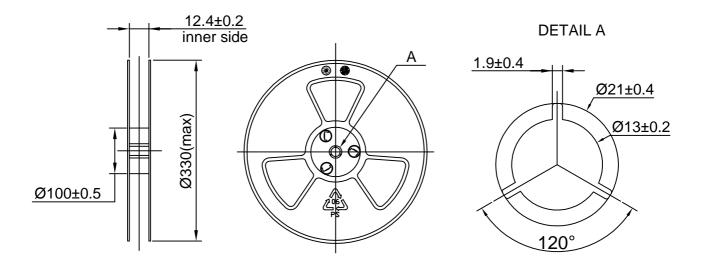


#### 9.2 Reel Dimension

7" reel for sample stage

13" reel will be provided for the mass production stage

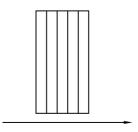
The following is 13" reel dimensions (unit:mm)



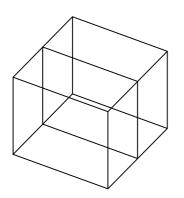
## 9.3 The Content of Box(13" reel)



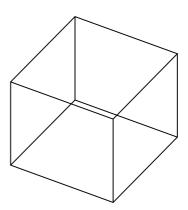
Packing (4,000PCS)



Inner Box(20,000PCS) (340mm×135mm×355mm)



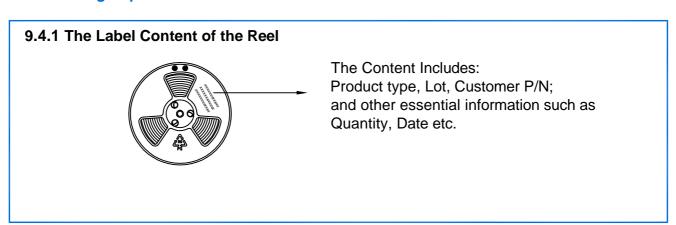
Two Inner Box(40,000PCS)

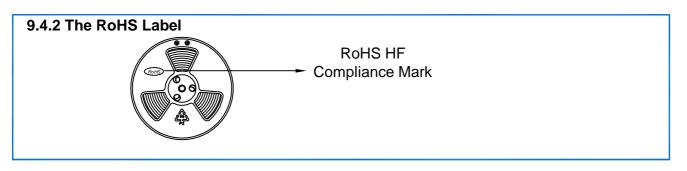


Outer Box(40,000PCS) (370mm×300mm×390mm)



#### 9.4 Packing Explain





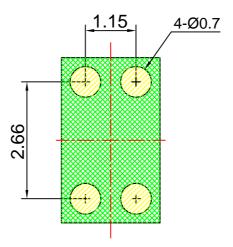
## 10 Storage and Transportation

- 10.1 Keep MEMS MIC in warehouse with less than 75% humidity and without sudden temperature change, acid air, any other harmful air or strong magnetic field. Recommend storage period no more than 1 year and floor life(out of bag) at factory no more than 4 weeks.
- 10.2 The MEMS MIC with normal pack can be transported by ordinary conveyances. Please protect products against moist, shock, sunburn and pressure during transportation.
- 10.3 Storage Temperature Range :  $-40^{\circ}\text{C} \sim +70^{\circ}\text{C}$  (Microphone units with package)
- 10.4 Operating Temperature Range: -40°C∼+100°C

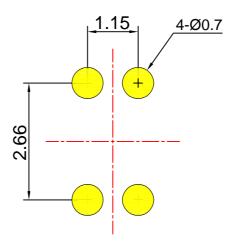


## 11 Land Pattern Recommendation

## 11.1 The Pattern of MIC Pad(Unit:mm)



## 11.2 Recommended Soldering Surface Land Pattern



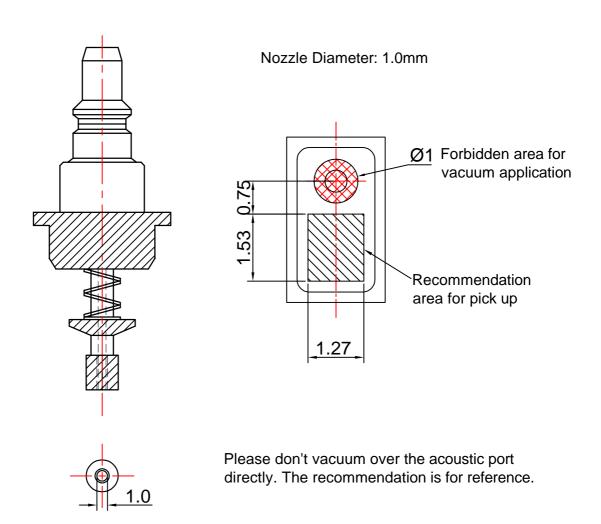


## 12 Soldering Recommendation

## 12.1 Soldering Machine Condition

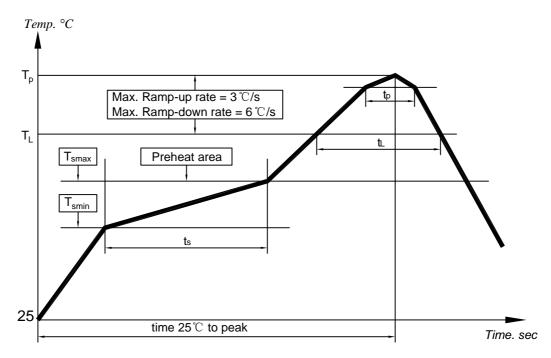
Temperature Control	8 zones
Heater Type	Hot Air
Solder Type	Lead-free

## 12.2 The Drawing and Dimension of Nozzle





#### 12.3 Reflow Profile



## **Key Features of The Profile:**

Average Ramp-up rate( $T_{smax}$ to $T_p$ )	3℃/s max.
Preheat : Temperature $Min(T_{smin})$ Temperature $Max(T_{smax})$ Time $(T_{smin}$ to $T_{smax})(t_s)$	150℃ 200℃ 60~180s
Time maintained above :	217℃ 60~150s
Peak Temperature(T <sub>p</sub> )	260℃
Time within $5^{\circ}\!$	30~40s
Ramp-down rate(T <sub>p</sub> to T <sub>smax</sub> )	6℃/s max
Time 25℃ to Peak Temperature	8min max

When MEMS MIC is soldered on PCB, the reflow profile is set according to solder paste and the thickness of PCB etc.



#### 12.4 Rework

- (1) 250°C~270°C, maximum 30 sec, Peak temperature 330°C.
- (2) Wind speed: 15L/m.
- (3) It is very important not to put a heatgun over the acoustic port of the microphone.

#### 13 Cautions

#### 13.1 Board Wash Restrictions

It is very important not to wash the PCBA after reflow process, otherwise this could damage the microphone.

#### 13.2 Nozzle Restrictions

It is very important not to be put a nozzle over the acoustic hole of the microphone, otherwise this could damage the microphone.

#### 13.3 Blowing Restrictions

It is very important not to blow the acoustic port of the microphone directly, otherwise this could damage the microphone.

#### 13.4 Ultrasonic Restrictions

It is very important not to use ultrasonic process. otherwise this could damage the microphone.

#### 13.5 Case Adaption to Pressure Restrictions

It is very important not to press the case with a force larger than 2.5kgf, otherwise this would damage the microphone.

## 14 Output Inspection Standard

Output inspection standard is executed according to <<ISO2859-1:1999>>.

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